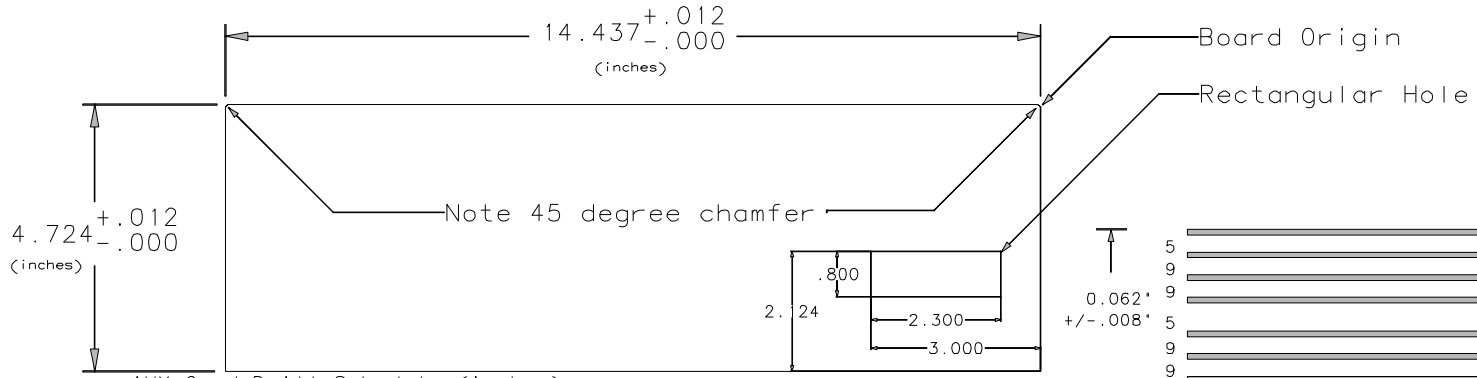
DWG. NO. B-2493 | SH 1 | REV. A

Schematic Drawing: C-2511

Assembly Drawing: C-2513



Layer Order:

AUX Card Drill Schedule (inches)

FHS	COUNT	PLATED	COMMENT
.016	760	YES	
.0236	117	YES	Note 11
.033	104	YES	
.035	136	YES	
.040	140	YES	
.042	20	YES	
.050	10	YES	
.055	4	NO	
.059	8	YES	
.079	8	YES	
.09	4	NO	
.095	4	YES	
.106	11	NO	
.1063	12	NO	
.113	9	NO	

Board Characteristics:

1. Material: FR4, Tg > 170C.
2. Board Thickness: 0.062"+/-0.008" (2.36 +/- .20mm).
3. Minimum Trace Width 0.006" on all layers, minimum clearrence 0.006" on all layers.
4. 1 oz Copper for top, bottom and power layers; 1/2 oz Copper for embedded signal layers.
5. Electroless Nickel/Immersion Gold plating; apply solder mask.
6. Silkscreen on Both Sides
7. Interlayer spacing : as specified.
8. FHS tolerances : +/- 0.002" unless specified otherwise.
9. Impedance: 55 Ohm +/- 5 Ohm for 0.006" traces on all layers.
10. Perform TDR test on every board using existing test traces on board.
11. This is a pressfit tech. thru hole with the following specs:
    - Finished plated hole size: 0.59 - 0.65 mm
    - Drilled hole size: 0.7mm +/- 0.02mm
    - Thickness of thru hole plating:
      min 25 μm Cu, 2.5-5 μm Ni, 0.05-0.2 μm Au (Electroless Ni/Immersion Au).
12. Films 4 and 5 are identical.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .008

DO NOT SCALE DRAWING

TREATMENT

FINISH

SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS		DATE
DRAWN	M. Bogdan	12/16/02
CHECKED	H. Sanders	12/16/02
ISSUED		

THE UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE CDF Level 2 PULSAR-Aux Board Specification Drawing

SIZE B | FSCM NO. | DWG. NO. B-2512 | REV. A

SCALE 1/2 | SHEET 1 of 1

THIS SHEET IS COMPUTER GENERATED